SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

An adhesive sheet 8 having rigidity and a portion 8b which adheres to the back surface of the outside portion of the film circuit is used. Specifically, there is used the adhesive sheet 8 which is obtained by forming cushioning adhesive sheet layers 9, 11 on both the surfaces of the rigid sheet layer 10 formed of stainless or the like. Further, the rigid sheet layer 10 is also used for electrostatic shield. The co-planarity of external terminals (soldering balls) is enhanced without vainly increasing the weight of a semiconductor device, and further the resistance to high-frequency noses in the semiconductor device is enhanced.

FIGURE 4A